

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

5N10-MS

Product specification

General Description

The 5N10-MS uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications.

Key Performance Parametes

Parameter	Value	Unit
V_{DS}	100	V
$R_{DS(ON_TYP)}$	90	m Ω
I_D	5	A
Q_G	4.4	nC

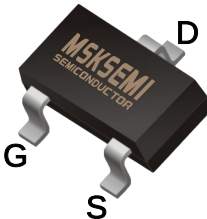
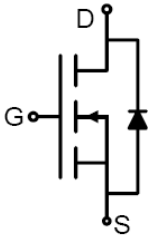
Features

- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

Applications

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

Reference News

SOT-23	N-Channel and P-Channel	Marking
		

Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0\text{V}$)	100	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0\text{V}$)	± 20	V
I_D	Drain Current-Continuous($T_A=25^{\circ}\text{C}$)	5	A
	Drain Current-Continuous($T_A=100^{\circ}\text{C}$)	1.3	A
$I_{DM}(\text{pulse})$	Drain Current-Continuous@ Current-Pulsed (Note 1)	8.4	A
P_D	Maximum Power Dissipation($T_A=25^{\circ}\text{C}$)	1.4	W
	Maximum Power Dissipation($T_A=100^{\circ}\text{C}$)	0.5	W
E_{AS}	Avalanche energy (Note 2)	16	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}\text{C}$

Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		91	$^{\circ}\text{C/W}$

Electrical Characteristics (T_J=25°C unless otherwise noted)

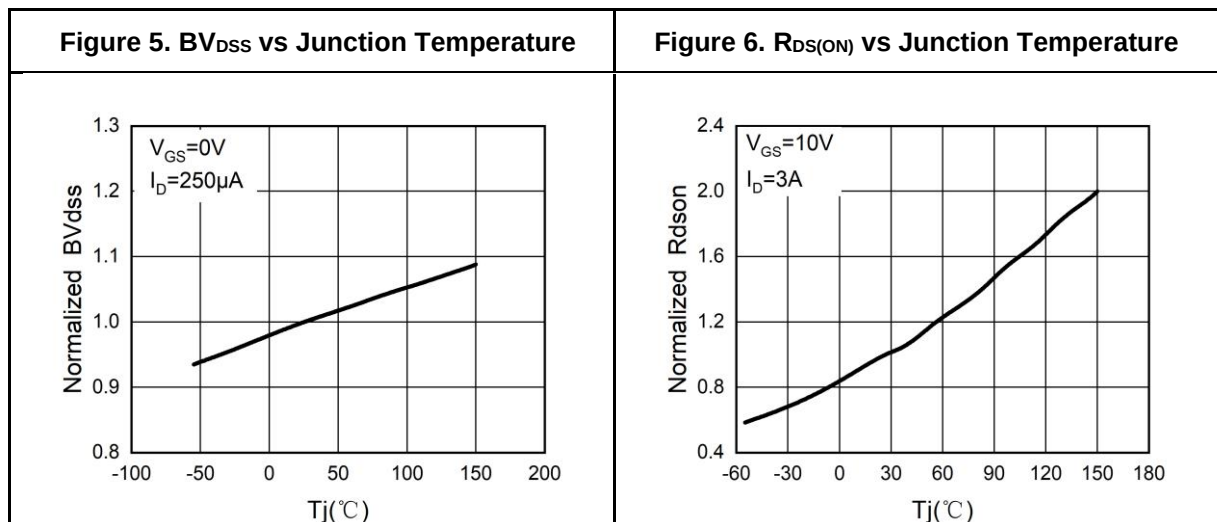
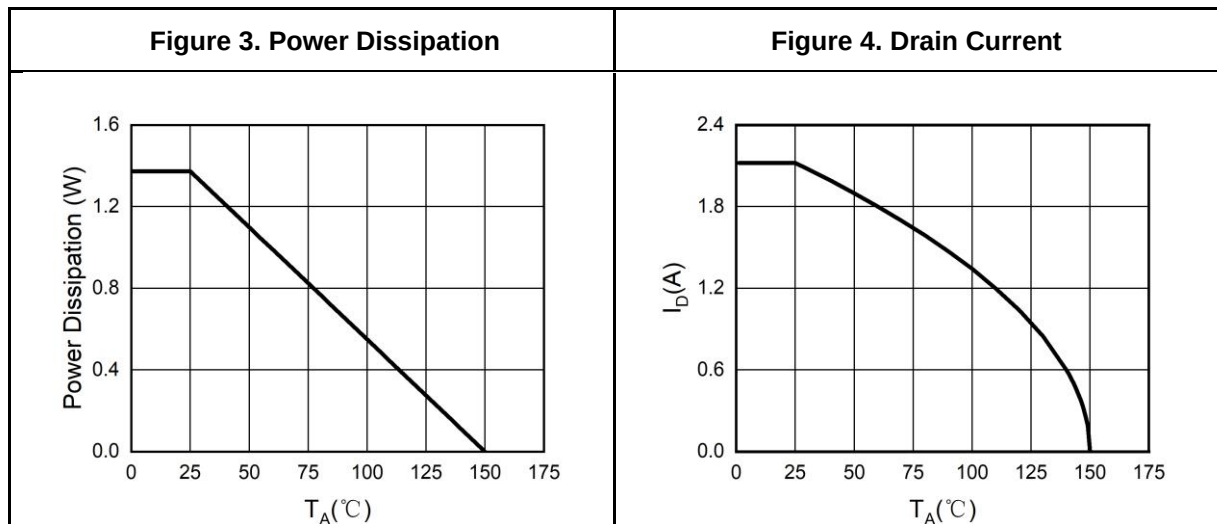
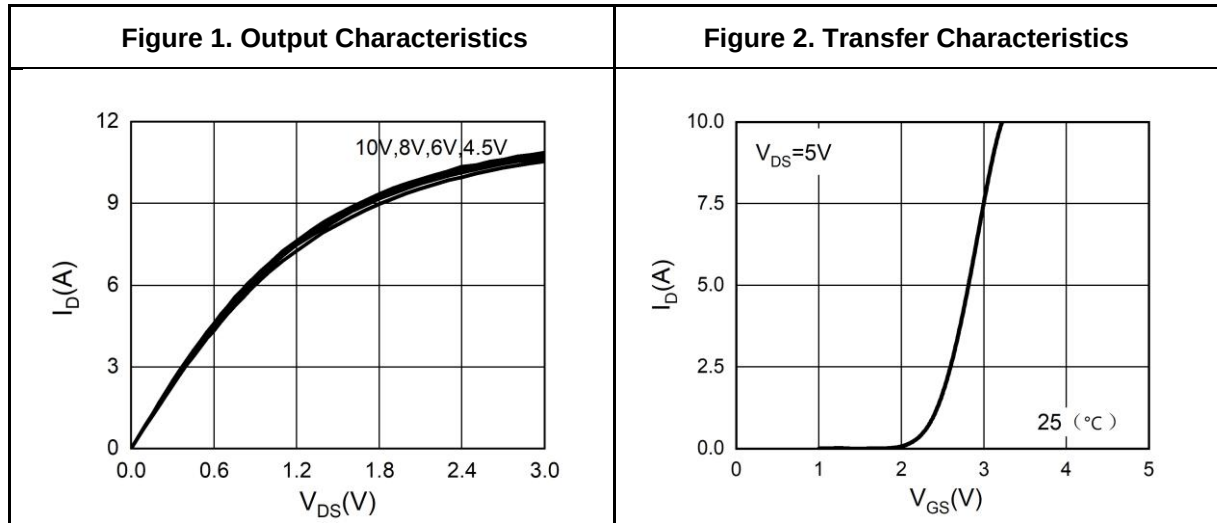
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	100			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =100V, V _{GS} =0V T _J =25℃			1	μA
		V _{DS} =100V, V _{GS} =0V T _J =125℃			100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.2		1.8	V
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =3A		6.2		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =3A T _J =25℃		90	105	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =2A T _J =25℃		110	125	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =50V,V _{GS} =0 V, f=1.0MHz		635		pF
C _{oss}	Output Capacitance			24		pF
C _{rss}	Reverse Transfer Capacitance			19		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz		1		Ω
Switching Parameters						
t _{d(on)}	Turn-on Delay Time	V _{GS} =10V, V _{DS} =50V, R _L =16.7Ω, R _{GEN} =3Ω		16		nS
t _r	Turn-on Rise Time			4		nS
t _{d(off)}	Turn-Off Delay Time			20		nS
t _f	Turn-Off Fall Time			3.6		nS
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =50V, I _D =3A		4.4		nC
Q _{gs}	Gate-Source Charge			1.3		nC
Q _{gd}	Gate-Drain Charge			1.1		nC
Source-Drain Diode Characteristics						
I _{SD}	Source-Drain Current (Body Diode)				5	A
V _{SD}	Forward on Voltage (Note 3)	V _{GS} =0V, I _S =3A			1.2	V
t _{rr}	Reverse Recovery Time	I _F =3A, dI/dt=100A/μs		20		ns
Q _{rr}	Reverse Recovery Charge	I _F =3A, dI/dt=100A/μs		13		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

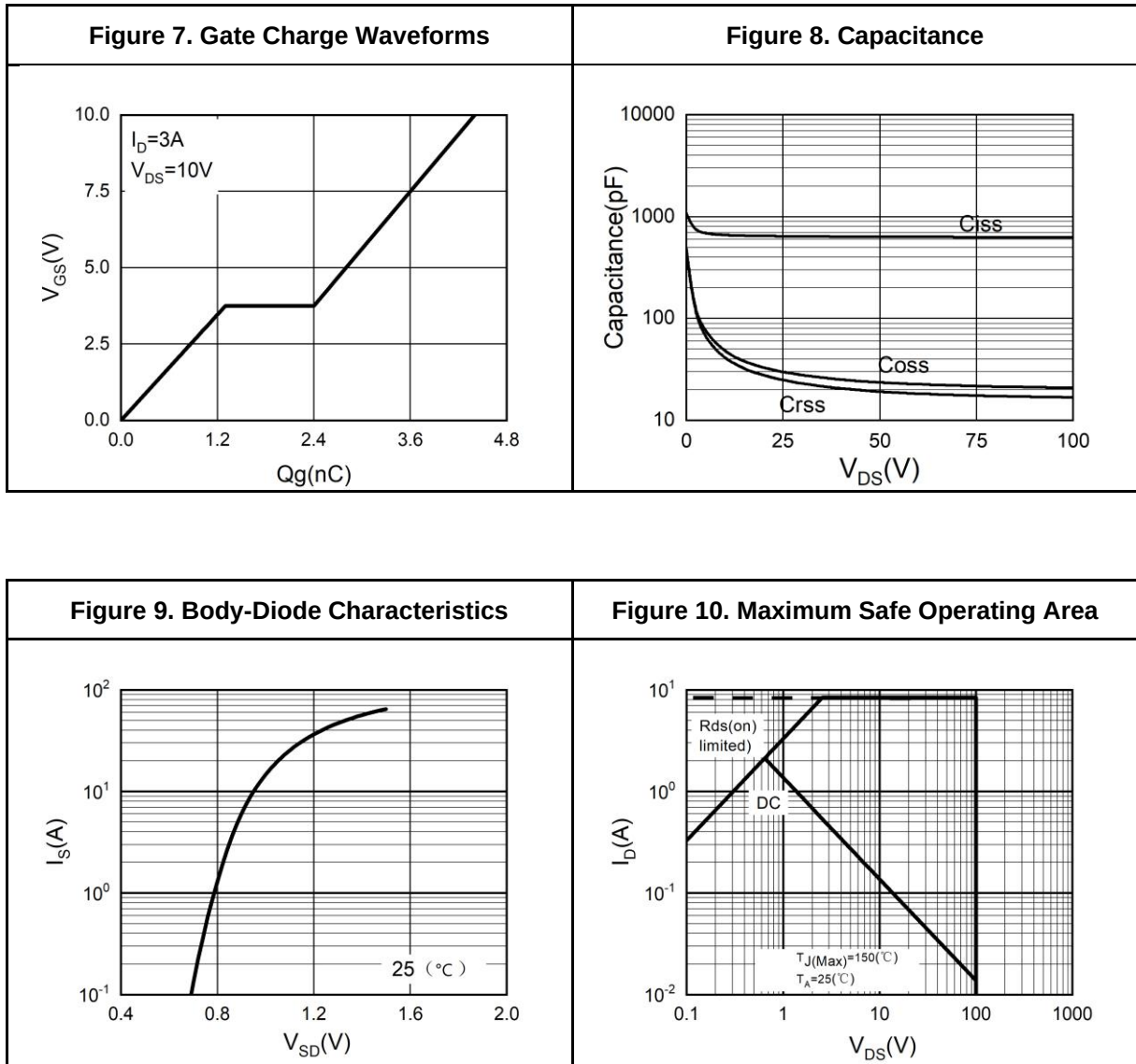
Notes 2.EAS condition: T_J=25°C, V_{DD}=60V, V_G=10V, R_g=25Ω, L=0.5mH.

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

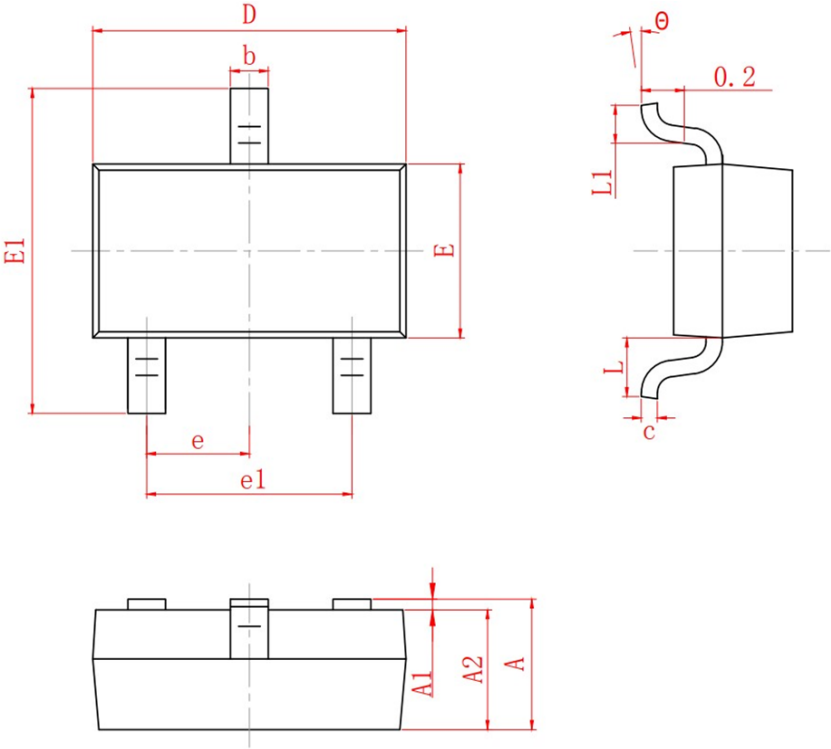
Typical Electrical And Thermal Characteristics (Curves)



Typical Electrical And Thermal Characteristics (Curves)



SOT-23 Package Information



SYMBOL	MIN	NOM	MAX
A	0.90	1.05	1.20
A1	0.00	0.05	0.10
A2	0.90	1.00	1.10
b	0.30	0.40	0.50
c	0.08	0.10	0.15
D	2.80	2.90	3.00
E	1.20	1.30	1.40
E1	2.30	2.40	2.50
L	0.30	0.40	0.50
θ	0°	5°	10°
L1	0.55 REF		
e	0.95 BSC		
e1	1.90 REF		

REEL SPECIFICATION

P/N	PKG	QTY
5N10-MS	SOT-23	3000

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